

semiconductor packaging news

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VIEWPOINT 2020: Don Gudczauskas, Vice President, Uyemura USA

In the semiconductor industry, smaller form factors, faster response times, and harsh environment adaptability continue to push the industry into new developments.

As a specialty chemical provider, we clearly see the need to form circuits with excellent copper thickness uniformity, produce smoother copper to reduce signal loss, and provide final finishes with lower electrical resistance to minimize insertion loss.

Narrower trace requirements have shifted some of the focus in final finishes away from nickel, both because of deposit thickness and electrical resistivity concerns. Reducing or eliminating nickel brings reliable Palladium and Gold plating processes to the forefront, and this is one specific area where Uyemura has dedicated extensive research resources over time. The need to electrolytically build copper pillars and posts with high current density remains a high priority.

It's an exciting time to work in these areas with our valued supply chain partners, and we look forward to a successful 2020 despite the special challenges of trade tariffs and contagions.

**Don Gudczauskas, Vice President
Uyemura USA**



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Vice President,
Uyemura USA



uyemura.com

UYEMURA Corporate Headquarters:

3990 Concourse, #425 • Ontario, CA 91764 • ph: (909) 466-5635

UYEMURA Tech Center:

240 Town Line Road • Southington, CT 06489 • ph: (860) 793-4011

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